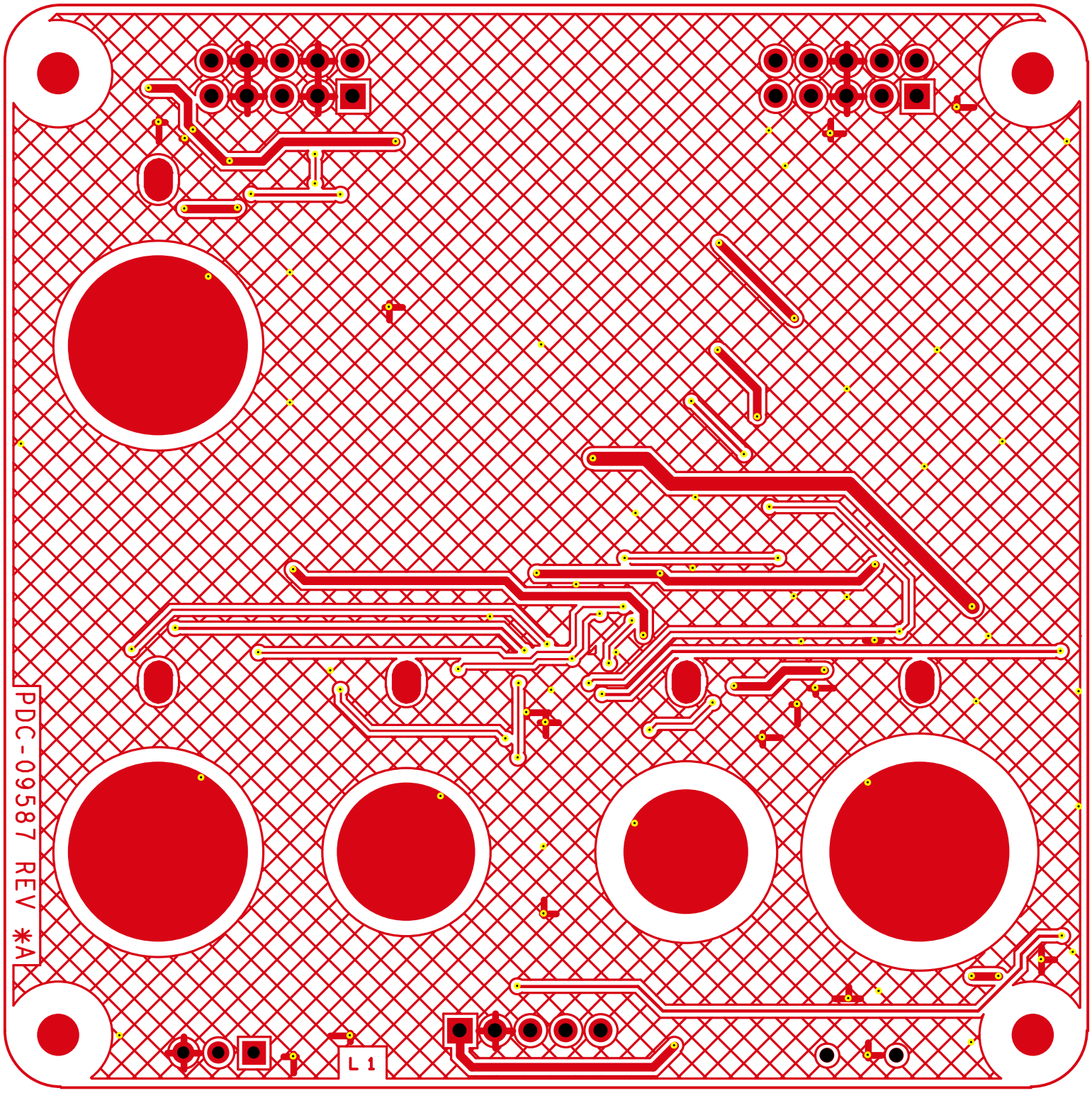
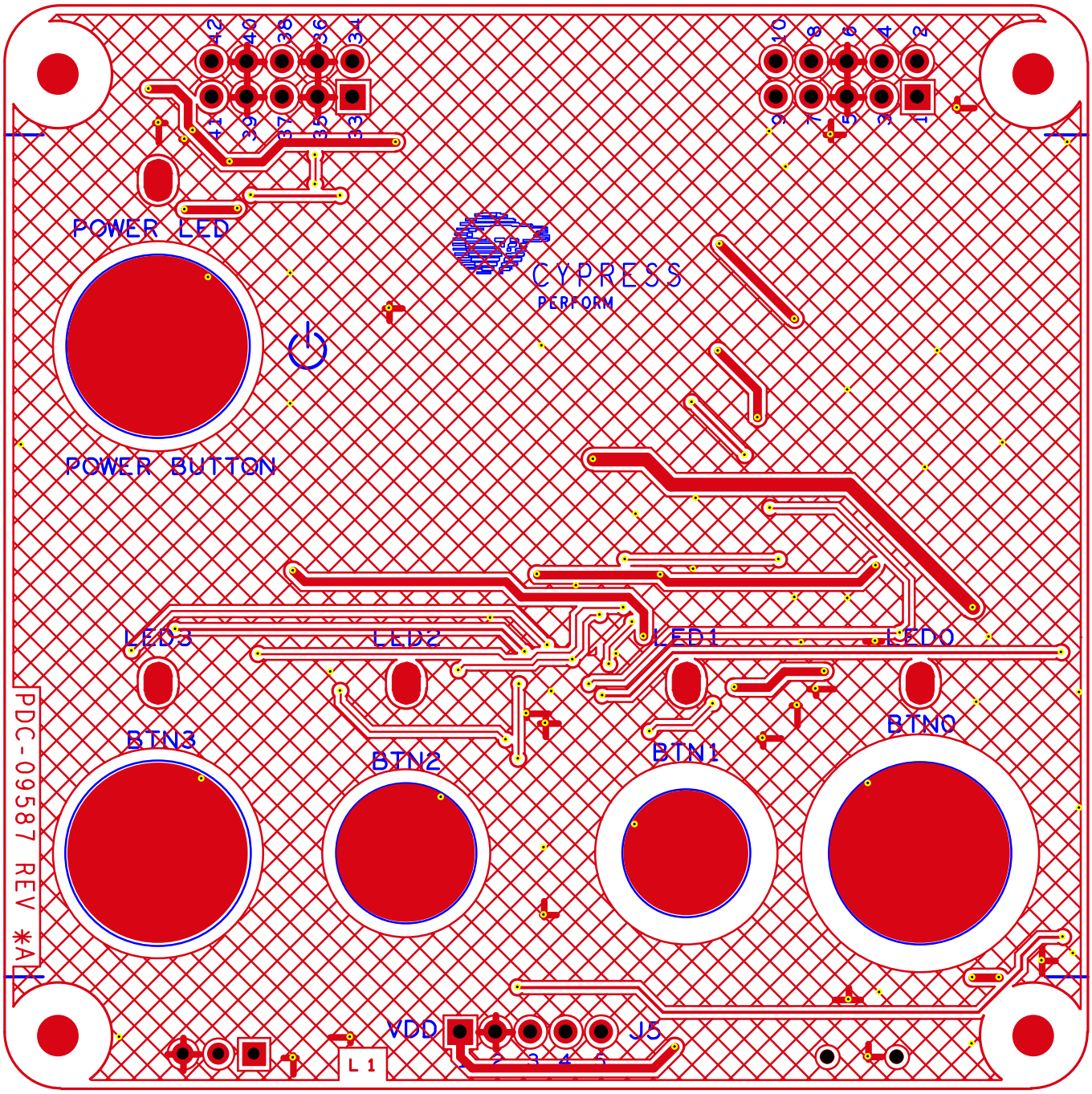
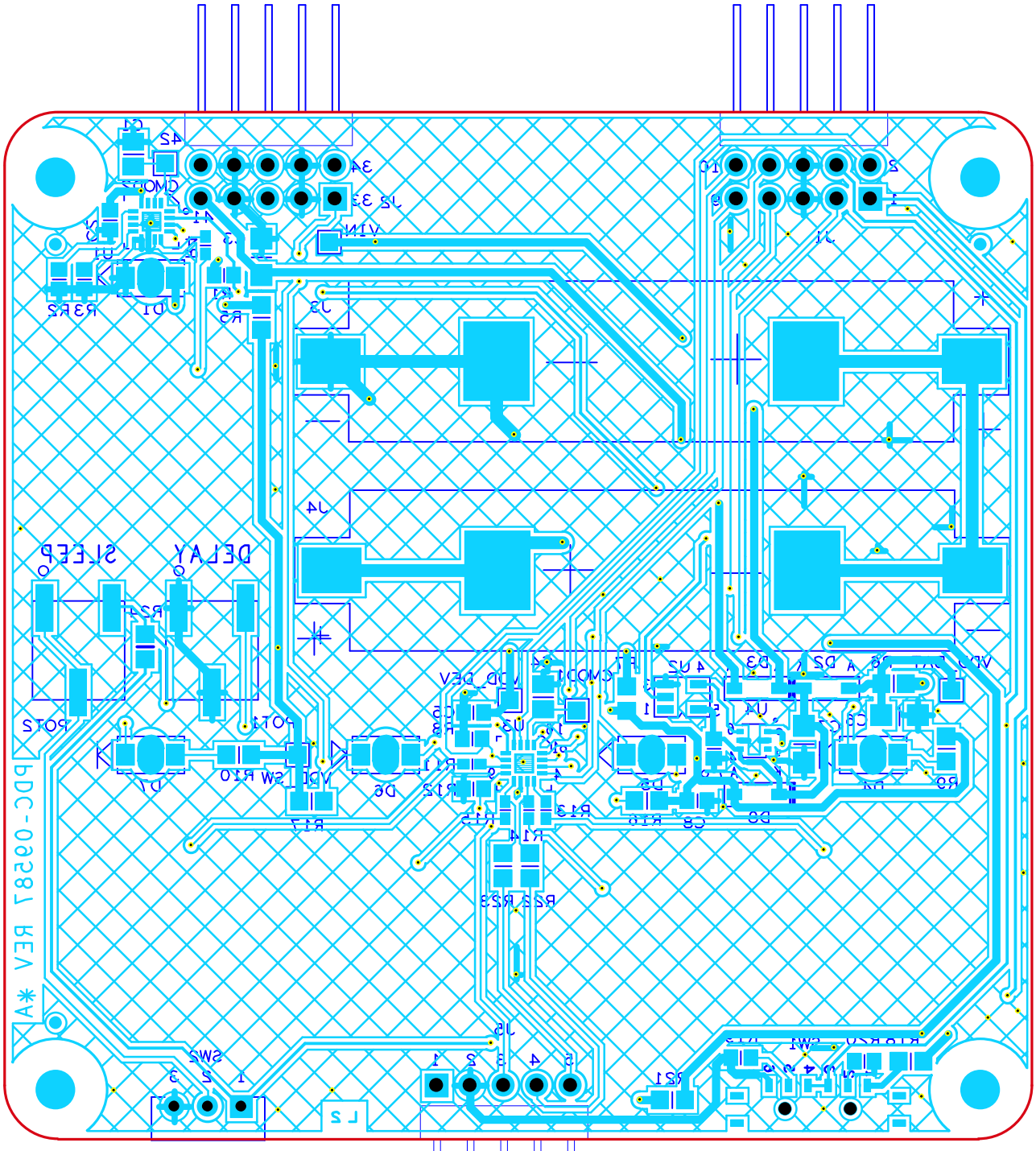


PDC-09587 REV *A PRIMARY SIDE

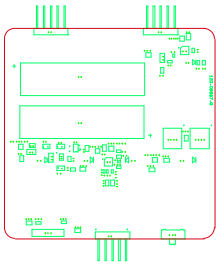
PDC-09587 REV *A SECONDARY SIDE



PDC-09587 REV *A PRIMARY SIDE
PDC-09587 REV *A PRIMARY SILKSCREEN



PDC-09587 REV *A SECONDARY SILKSCREEN



PDC-09587 REV *A SECONDARY ASSEMBLY

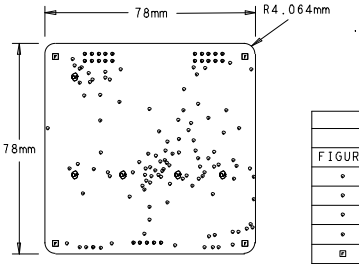
CYPRESS SEMICONDUCTOR

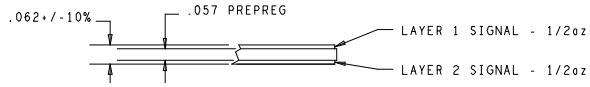
ASSEMBLY DRAWING
CY3280-MBR
SMARTSENSE EVALUATION KIT

SIZE	FSCM NO	DWG NO	REV
C		120-09587-0	*A

SCALE: 1/1 SHEET: 2 OF 2

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
01	RELEASE FOR MANUFACTURING.	11/16/09	RKAD
02	CHANGE CONNECTOR J3,J14	02/12/10	RKAD
03	INCREASE BRD SIZE,CONNECTOR TO THROUGH HOLE, POWER BUTTON TO CAPSENCE AND ADDED ONBRD BATTERY	09/16/10	PKRB
04	ADDED SWITCH TO SUPPORT 1.7V	09/25/10	PKRB
**	FINAL RELEASE	10/13/10	PKRB
*A	PAD STACK CHANGED FOR U1,U3,BAT	02/04/11	PKRB





DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
○	8.0	+3.0/-8.0	PLATED	107
○	35.0	+3.0/-3.0	PLATED	3
○	40.0	+3.0/-3.0	PLATED	2
○	42.0	+3.0/-3.0	PLATED	25
⊡	125.0	+2.0/-2.0	NON-PLATED	4
⊗	120.0x90.0	+5.0/-5.0	NON-PLATED	5

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED
2. MATERIAL:
   A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol.
      UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
   COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO PLACE DATE CODE AND LOGO ON SECONDARY SIDE IN ETCH (PREFERRED) OR SILKSCREEN.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR **BLACK**
7. FINISH:
   A. SHALL BE ELECTROLYTIC NICKEL/GOLD. ELECTROLESS NIKEL / IMMERSION GOLD. (ENIG)
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY AND SHALL BE MARKED IN COPPER ON SECONDARY SIDE OF BOARD WITH VENDORS UL IDENT. FLAMABILITY RATING (94-V0). DATE CODE (WWYY). AND RoHS COMPILANT SYMBOL.
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .010 in/in.
11. TESTING:
   A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
   B. T-LINE IMPEDENCE TO BE TESTED OR GURANTEED WITHIN 10% IF SPECIFIED IN THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE
DIMENSIONS ARE IN INCHES	DRAWN PKRB	10/13/10
TOLERANCES ON; ANGLES +/- 2°	CHECKED RKAD	02/04/11
2 PL DECIMALS +/- .010	ENGRG PKRB	02/04/11
3 PL DECIMALS +/- .005	ISSUED	
THIRD ANGLE PROJECTIONS		

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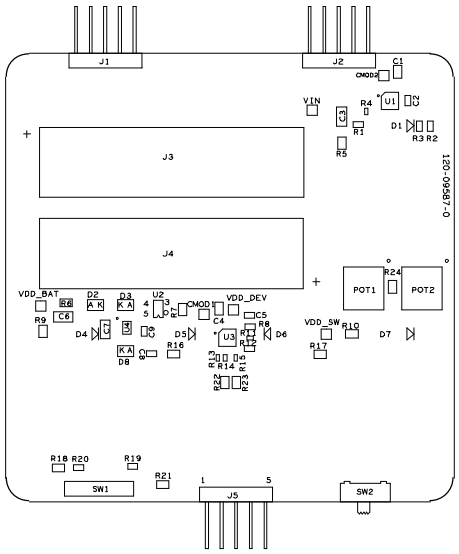
CYPRESS SEMICONDUCTOR

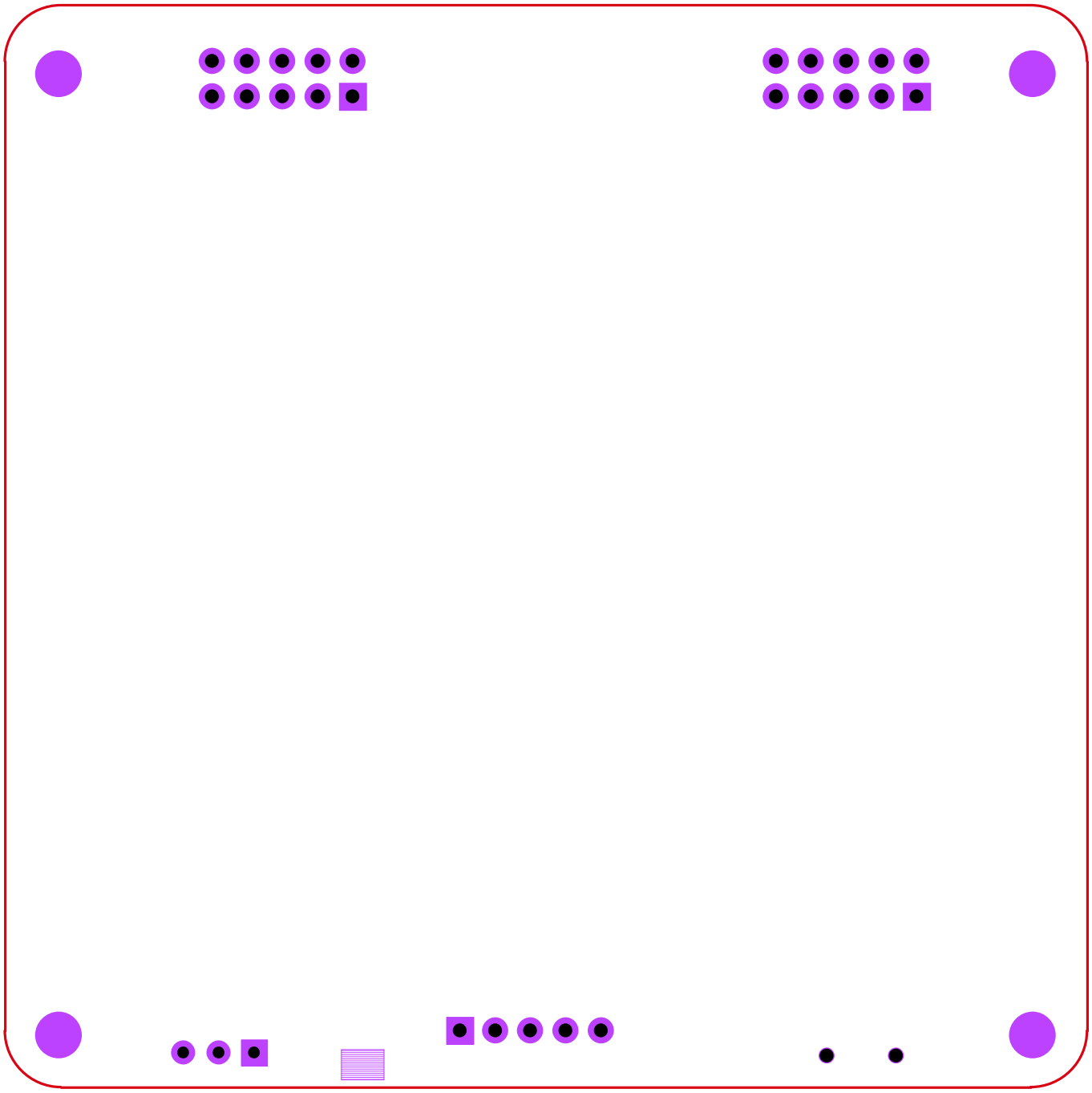
FABRICATION DRAWING
CY3280-MBR
SMARTSENSE EVALUATION KIT

SIZE	FSCM NO	DWG NO	REV
C		PDC-09587	

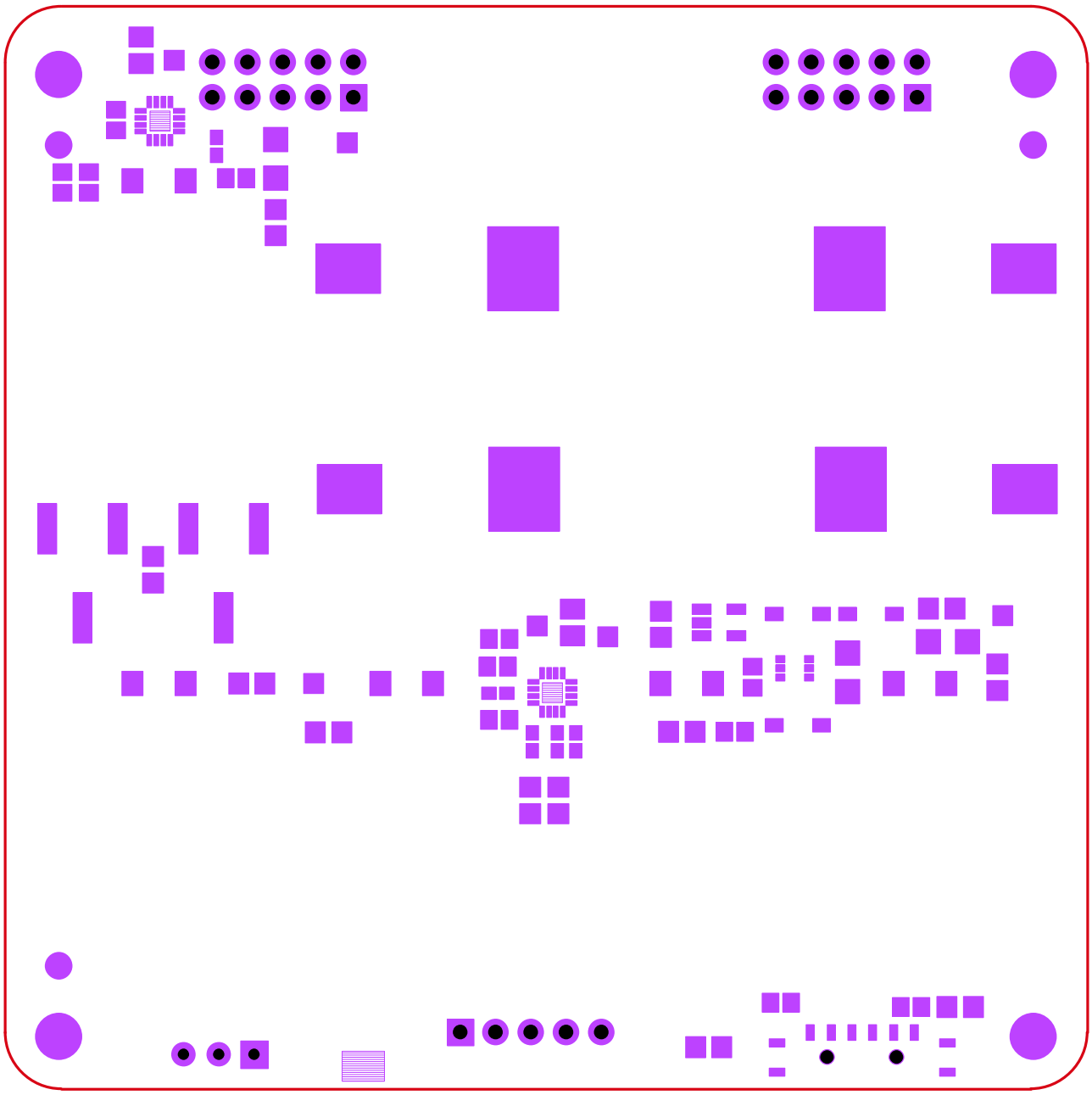
SCALE: 1/1 SHEET: 1 OF 1



PDC-09587 REV *A SECONDARY ASSEMBLY



PDC-09587 REV *A PRIMARY SOLDERMASK



PDC-09587 REV *A SECONDARY SOLDERMASK